

# HEF4049B-Q100

## Hex inverting buffers

Rev. 3 — 17 June 2016

Product data sheet

## 1. General description

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The HEF4049B-Q100 provides six inverting buffers with high current output capability suitable for driving TTL or high capacitive loads. Since input voltages in excess of the supply voltage of the buffers are permitted, the buffers may also be used to convert logic levels of up to 15 V to standard TTL levels. Their guaranteed fan-out into common bipolar logic elements is shown in [Table 3](#).

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 3) and is suitable for use in automotive applications.

## 2. Features and benefits

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- Automotive product qualification in accordance with AEC-Q100 (Grade 3)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$
- Accepts input voltages in excess of the supply voltage
- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )
- Complies with JEDEC standard JESD 13-B

## 3. Applications

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- Industrial
- LOCMOS (Local Oxidation CMOS) to DTL/TTL converter
- HIGH sink current for driving two TTL loads
- HIGH-to-LOW level logic conversion

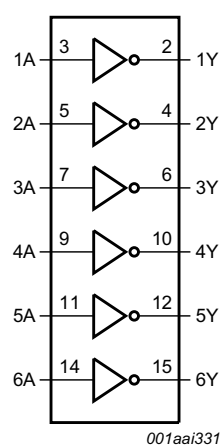


## 4. Ordering information

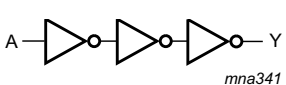
**Table 1. Ordering information**  
All types operate from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$ .

Type number	Package		Version
	Name	Description	
HEF4049BT-Q100	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

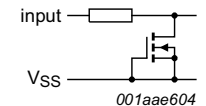
## 5. Functional diagram



001aa1331



mna341



001aae604

**Fig 1. Logic symbol**

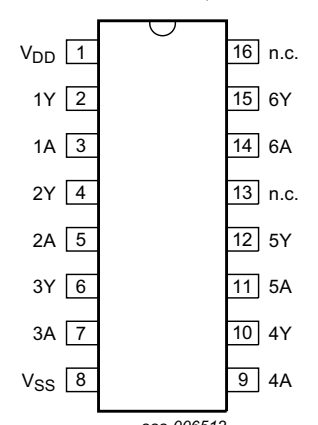
**Fig 2. Logic diagram for one gate**

**Fig 3. Input protection circuit**

## 6. Pinning information

### 6.1 Pinning

**HEF4049B-Q100**



aaa-006512

**Fig 4. Pin configuration**

## 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
V <sub>DD</sub>	1	supply voltage
1Y to 6Y	2, 4, 6, 10, 12, 15	output
1A to 6A	3, 5, 7, 9, 11, 14	input
V <sub>SS</sub>	8	ground supply voltage
n.c.	13, 16	not connected

## 7. Functional description

Table 3. Guaranteed fan-out

Driven element	Guaranteed fan-out
Standard TTL	2
74 LS	9
74 L	16

## 8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DD</sub>	supply voltage		-0.5	+18	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V	-10	-	mA
V <sub>I</sub>	input voltage		-0.5	+18	V
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>DD</sub> + 0.5 V	-	±10	mA
I <sub>I/O</sub>	input/output current		-	±10	mA
I <sub>DD</sub>	supply current		-	50	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>amb</sub>	ambient temperature		-40	+85	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> -40 °C to +85 °C <a href="#">[1]</a>	-	500	mW
P	power dissipation	per output	-	100	mW

[1] For SO16 package: P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.

## 9. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>DD</sub>	supply voltage		3	-	15	V
V <sub>I</sub>	input voltage		0	-	15	V
T <sub>amb</sub>	ambient temperature	in free air	-40	-	+85	°C

Table 5. Recommended operating conditions ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5\text{ V}$	-	-	3.75	$\mu\text{s/V}$
		$V_{DD} = 10\text{ V}$	-	-	0.5	$\mu\text{s/V}$
		$V_{DD} = 15\text{ V}$	-	-	0.08	$\mu\text{s/V}$

## 10. Static characteristics

Table 6. Static characteristics

$V_{SS} = 0\text{ V}$ ;  $V_I = V_{SS}$  or  $V_{DD}$  unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	$T_{amb} = -40\text{ }^\circ\text{C}$		$T_{amb} = 25\text{ }^\circ\text{C}$		$T_{amb} = 85\text{ }^\circ\text{C}$		Unit
				Min	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
$V_{IL}$	LOW-level input voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
$V_{OH}$	HIGH-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
$V_{OL}$	LOW-level output voltage	$ I_O  < 1\text{ }\mu\text{A}$	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
$I_{OH}$	HIGH-level output current	$V_O = 2.5\text{ V}$	5 V	-1.7	-	-1.4	-	-1.1	-	mA
		$V_O = 4.6\text{ V}$	5 V	-0.52	-	-0.44	-	-0.36	-	mA
		$V_O = 9.5\text{ V}$	10 V	-1.3	-	-1.1	-	-0.9	-	mA
		$V_O = 13.5\text{ V}$	15 V	-3.6	-	-3.0	-	-2.4	-	mA
$I_{OL}$	LOW-level output current	$V_O = 0.4\text{ V}$	4.75 V	3.5	-	2.9	-	2.3	-	mA
		$V_O = 0.5\text{ V}$	10 V	12.0	-	10.0	-	8.0	-	mA
		$V_O = 1.5\text{ V}$	15 V	24.0	-	20.0	-	16.0	-	mA
$I_I$	input leakage current	$V_{DD} = 15\text{ V}$	15 V	-	$\pm 0.3$	-	$\pm 0.3$	-	$\pm 1.0$	$\mu\text{A}$
$I_{DD}$	supply current	$I_O = 0\text{ A}$	5 V	-	4.0	-	4.0	-	30	$\mu\text{A}$
			10 V	-	8.0	-	8.0	-	60	$\mu\text{A}$
			15 V	-	16.0	-	16.0	-	120	$\mu\text{A}$
$C_I$	input capacitance			-	-	-	7.5	-	-	pF

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**

$V_{SS} = 0\text{ V}$ ;  $C_L = 50\text{ pF}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ °C}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula	Min	Typ	Max	Unit
$t_{PHL}$	HIGH to LOW propagation delay	nA to nY; see <a href="#">Figure 5</a>	5 V <sup>[1]</sup>	$26\text{ ns} + (0.18\text{ ns/pF})C_L$	-	35	70	ns
			10 V	$11\text{ ns} + (0.08\text{ ns/pF})C_L$	-	15	30	ns
			15 V	$9\text{ ns} + (0.05\text{ ns/pF})C_L$	-	12	25	ns
$t_{PLH}$	LOW to HIGH propagation delay	nA to nY; see <a href="#">Figure 5</a>	5 V <sup>[1]</sup>	$23\text{ ns} + (0.55\text{ ns/pF})C_L$	-	50	100	ns
			10 V	$14\text{ ns} + (0.23\text{ ns/pF})C_L$	-	25	50	ns
			15 V	$12\text{ ns} + (0.16\text{ ns/pF})C_L$	-	20	40	ns
$t_{THL}$	HIGH to LOW output transition time	see <a href="#">Figure 5</a>	5 V <sup>[1]</sup>	$3\text{ ns} + (0.35\text{ ns/pF})C_L$	-	20	40	ns
			10 V	$3\text{ ns} + (0.14\text{ ns/pF})C_L$	-	10	20	ns
			15 V	$2\text{ ns} + (0.09\text{ ns/pF})C_L$	-	7	14	ns
$t_{TLH}$	LOW to HIGH output transition time	see <a href="#">Figure 5</a>	5 V <sup>[1]</sup>	$10\text{ ns} + (1.00\text{ ns/pF})C_L$	-	60	120	ns
			10 V	$9\text{ ns} + (0.42\text{ ns/pF})C_L$	-	30	60	ns
			15 V	$6\text{ ns} + (0.28\text{ ns/pF})C_L$	-	20	40	ns

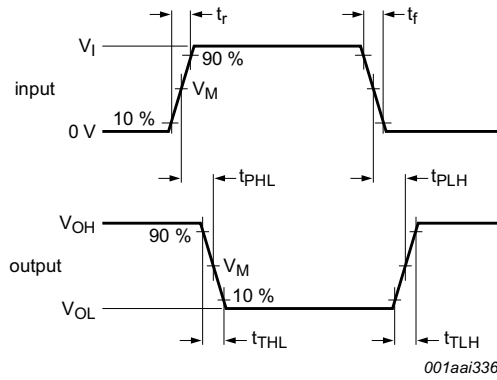
[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown ( $C_L$  in pF).

**Table 8. Dynamic power dissipation  $P_D$**

$P_D$  can be calculated from the formulas shown.  $V_{SS} = 0\text{ V}$ ;  $t_r = t_f \leq 20\text{ ns}$ ;  $T_{amb} = 25\text{ °C}$ .

Symbol	Parameter	$V_{DD}$	Typical formula for $P_D$ ( $\mu\text{W}$ )	where:
$P_D$	dynamic power dissipation	5 V	$P_D = 2500 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	$f_i$ = input frequency in MHz; $f_o$ = output frequency in MHz; $C_L$ = output load capacitance in pF; $V_{DD}$ = supply voltage in V; $\Sigma(f_o \times C_L)$ = sum of the outputs.
		10 V	$P_D = 11000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	
		15 V	$P_D = 35000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	

12. Waveforms

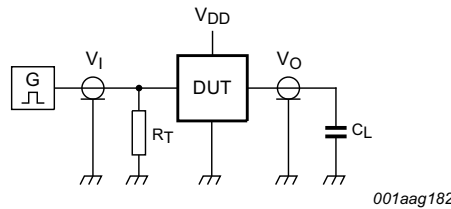


Measurement points are given in [Table 9](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 5. Input (nA) to output (nY) propagation delays and transition times**

**Table 9. Measurement points**

Input		Output		
$V_M$	$V_I$	$V_M$	$V_X$	$V_Y$
$0.5V_{DD}$	0 V to $V_{DD}$	$0.5V_{DD}$	$0.1V_{DD}$	$0.9V_{DD}$



Test data is given in [Table 10](#).  
 Definitions for test circuit:  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

**Fig 6. Test circuit for measuring switching times**

**Table 10. Test data**

Supply voltage	Input			Load
	$V_I$	$V_M$	$t_r, t_f$	$C_L$
5 V to 15 V	$V_{DD}$	$0.5V_I$	$\leq 20$ ns	50 pF

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

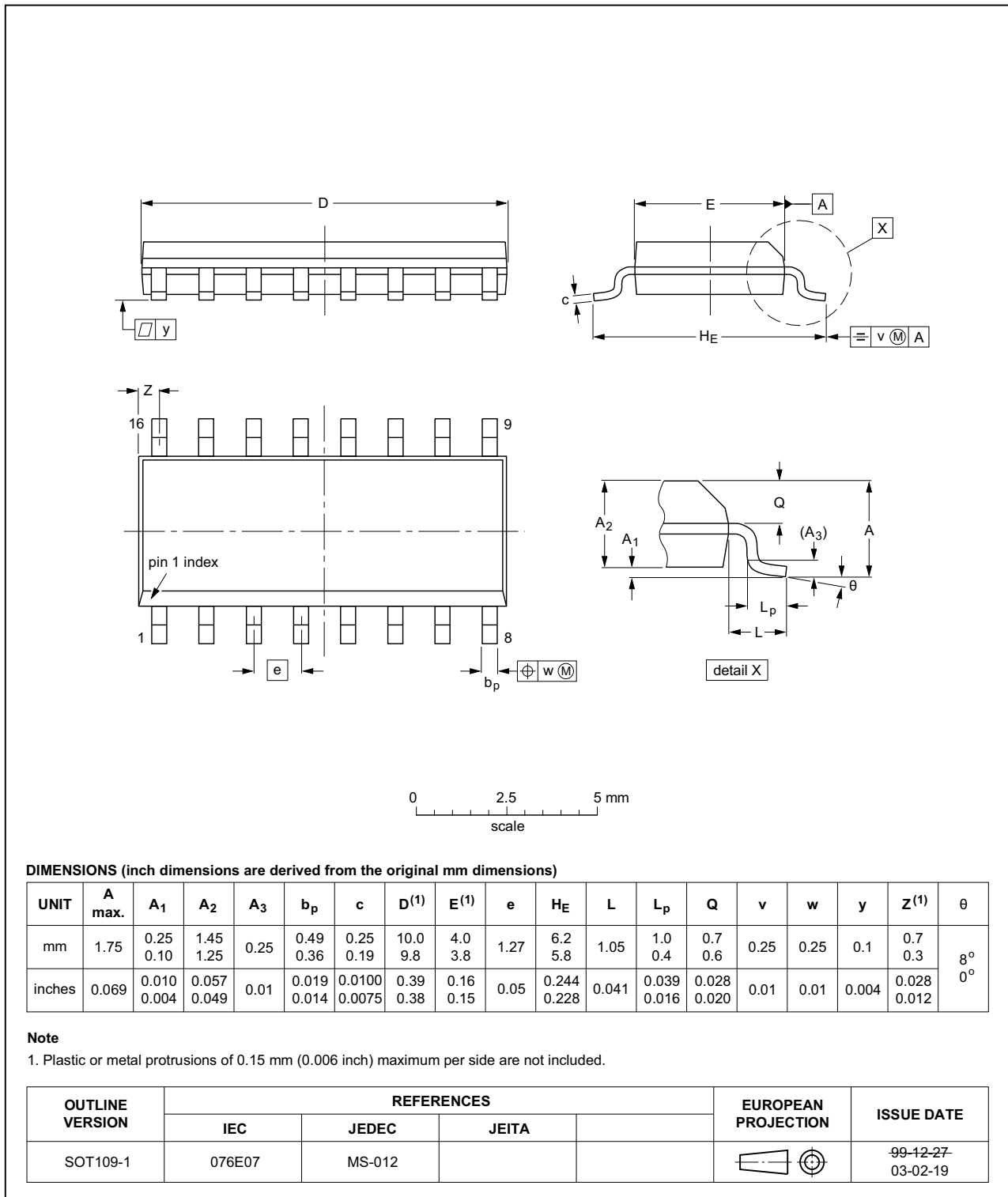


Fig 7. Package outline SOT109-1 (SO16)

## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
DTL	Diode Transistor Logic
LOC MOS	Local Oxidation CMOS
TTL	Transistor Transistor Logic
HBM	Human Body Model
ESD	ElectroStatic Discharge
MM	Machine Model
MIL	Military

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4049B_Q100 v.3	20160617	Product data sheet	-	HEF4049B_Q100 v.2
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Table 4</a>: condition for input clamping current changed (typo corrected).</li> <li>• <a href="#">Table 5</a>: maximum value for input voltage changed (typo corrected).</li> </ul>			
HEF4049B_Q100 v.2	20140910	Product data sheet	-	HEF4049B_Q100 v.1
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Section 2</a>: ESD protection: MIL-STD-833 changed to MIL-STD883</li> </ul>			
HEF4049B_Q100 v.1	20130228	Product data sheet	-	-



## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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